

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IAUS300N08S5N014T	**Issued**	16. May 2021
MA#	MA005344608		
Package	PG-HDSOP-16-2	**Weight***	854.46 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	6.440	0.75	0.75	7536	7536
leadframe	inorganic material	phosphorus	7723-14-0	0.143	0.02		168	
	non noble metal	iron	7439-89-6	0.477	0.06		559	
	non noble metal	copper	7440-50-8	476.748	55.79	55.87	557953	558680
wire	non noble metal	aluminium	7429-90-5	20.279	2.37	2.37	23733	23733
encapsulation	inorganic material	zincoxide	1314-13-2	3.242	0.38		3794	
	miscellaneous	miscellaneous	-	12.969	1.52		15178	
	plastics	epoxy resin	-	48.633	5.69		56916	
	inorganic material	silicondioxide	60676-86-0	259.375	30.36	37.95	303554	379442
leadfinish	non noble metal	tin	7440-31-5	6.684	0.78	0.78	7822	7822
plating	inorganic material	phosphorus	7723-14-0	0.013			15	
	non noble metal	nickel	7440-02-0	5.316	0.62	0.62	6221	6236
solder	non noble metal	tin	7440-31-5	0.107	0.01		125	
	noble metal	silver	7440-22-4	0.133	0.02		156	
	non noble metal	lead	7439-92-1	5.093	0.60	0.63	5960	6241
heatspreader	inorganic material	phosphorus	7723-14-0	0.003			3	
	non noble metal	iron	7439-89-6	0.009			10	
	non noble metal	copper	7440-50-8	8.798	1.03	1.03	10297	10310
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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